

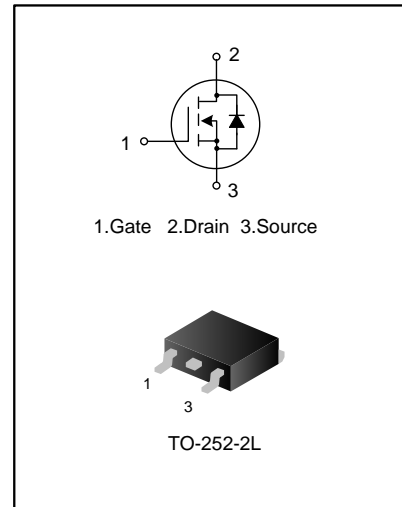
## 7A, 700V DP MOS POWER TRANSISTOR

### GENERAL DESCRIPTION

SVS7N70D is an N-channel enhancement mode high voltage power MOSFETs produced using Silan's DP MOS technology. It achieves low conduction loss and switching losses. It leads the design engineers to their power converters with high efficiency, high power density, and superior thermal behavior. Furthermore, it's universal applicable, i.e., suitable for hard and soft switching topologies.

### FEATURES

- ◆ 7A, 700V,  $R_{DS(on)(typ)}=0.52\Omega@V_{GS}=10V$
- ◆ New revolutionary high voltage technology
- ◆ Ultra low gate charge
- ◆ Periodic avalanche rated
- ◆ Extreme dv/dt rated
- ◆ High peak current capability



### ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing
SVS7N70DTR	TO-252-2L	SVS7N70D	Halogen free	Tape & Reel

**ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub>=25°C unless otherwise noted)**

Characteristics	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	700	V
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Drain Current	I <sub>D</sub>	T <sub>C</sub> =25°C	7.0
		T <sub>C</sub> =100°C	4
Drain Current Pulsed	I <sub>DM</sub>	25	A
Power Dissipation(T <sub>C</sub> =25°C) -Derate above	P <sub>D</sub>	73	W
		0.58	W/°C
Single Pulsed Avalanche Energy (Note)	E <sub>AS</sub>	260	mJ
Operation Junction Temperature Range	T <sub>J</sub>	-55~+150	°C
Storage Temperature Range	T <sub>stg</sub>	-55~+150	°C

**THERMAL CHARACTERISTICS**

Characteristics	Symbol	Ratings	Unit
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	1.71	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	62.00	°C/W

**ELECTRICAL CHARACTERISTICS (T<sub>C</sub>=25°C unless otherwise noted)**

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	700	--	--	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =700V, V <sub>GS</sub> =0V	--	--	1.0	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	--	--	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	2.0	--	4.0	V
Static Drain-Source On State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3.5A	--	0.52	0.6	Ω
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, f=1.0MHZ	--	520	--	pF
Output Capacitance	C <sub>oss</sub>		--	28.5	--	
Reverse Transfer Capacitance	C <sub>rss</sub>		--	3.0	--	
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =350V, I <sub>D</sub> =7.0A, V <sub>GS</sub> =10V, R <sub>G</sub> =24Ω  (Note 2,3)	--	12.9	--	ns
Turn-on Rise Time	t <sub>r</sub>		--	32.4	--	
Turn-off Delay Time	t <sub>d(off)</sub>		--	75.5	--	
Turn-off Fall Time	t <sub>f</sub>		--	28.1	--	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =560V, I <sub>D</sub> =7.0A, V <sub>GS</sub> =10V  (Note 2,3)	--	26.8	--	nC
Gate-Source Charge	Q <sub>gs</sub>		--	3.57	--	
Gate-Drain Charge	Q <sub>gd</sub>		--	16.8	--	

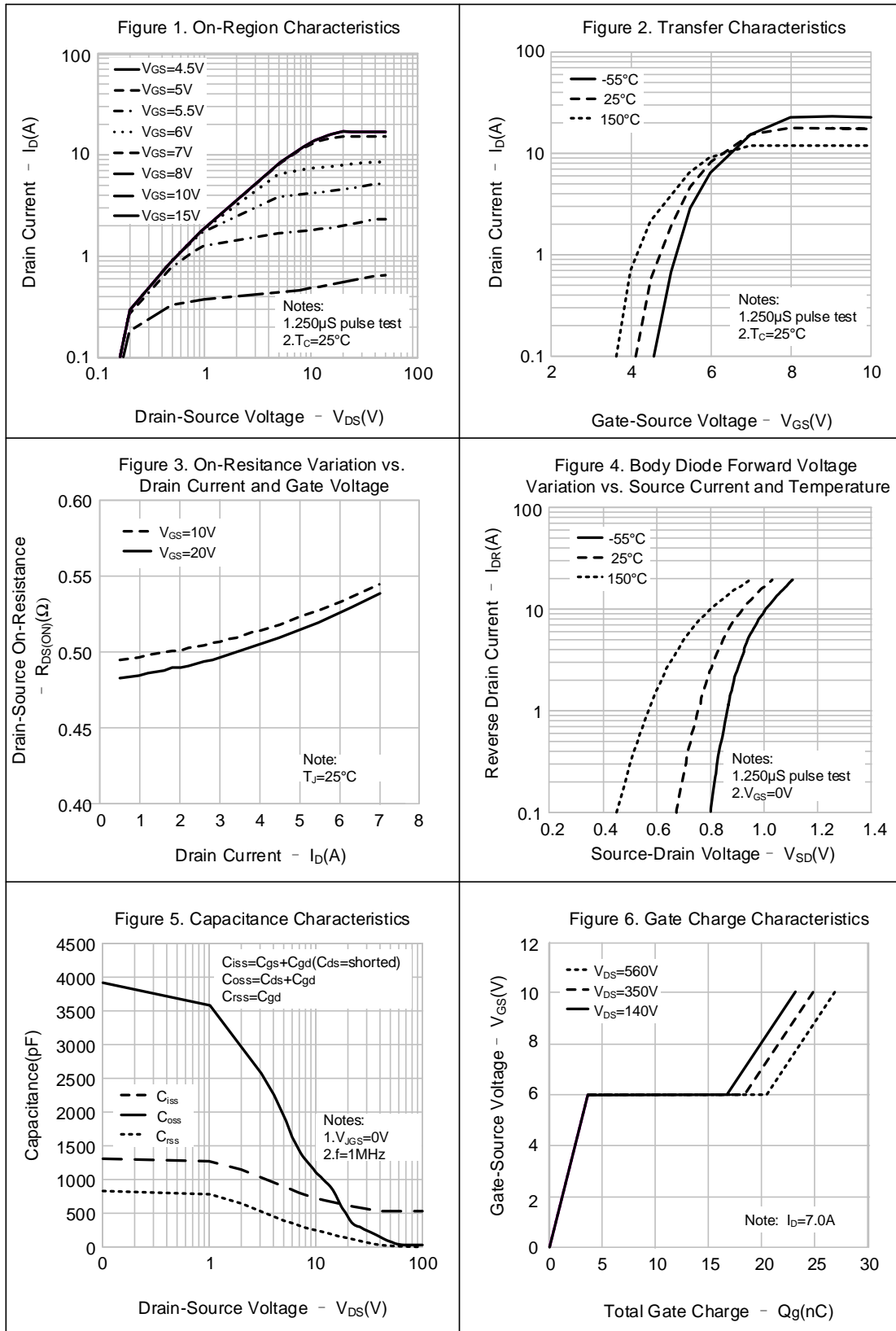
## SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	$I_S$	Integral Reverse P-N Junction	--	--	7.0	A
Pulsed Source Current	$I_{SM}$	Diode in the MOSFET	--	--	25	
Diode Forward Voltage	$V_{SD}$	$I_S=7.0A, V_{GS}=0V$	--	--	1.4	V
Reverse Recovery Time	$T_{rr}$	$I_S=7.0A, V_{GS}=0V,$	--	350	--	ns
Reverse Recovery Charge	$Q_{rr}$	$dI_F/dt=100A/\mu s$	--	3.2	--	$\mu C$

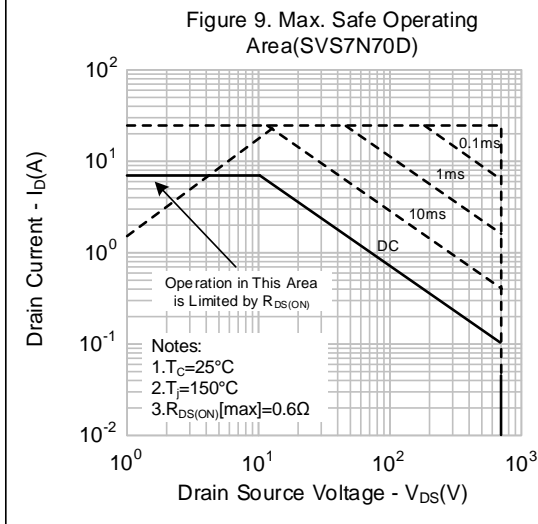
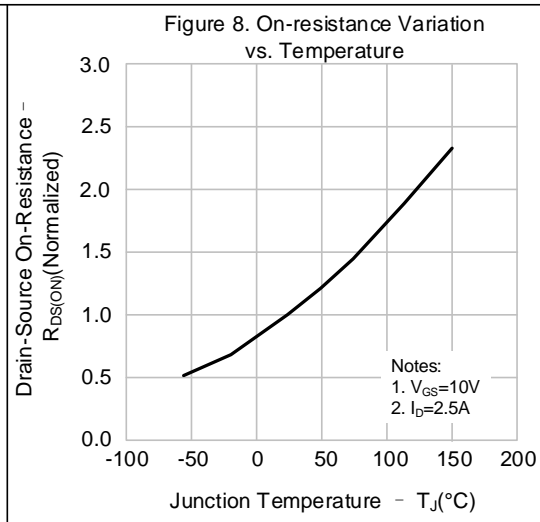
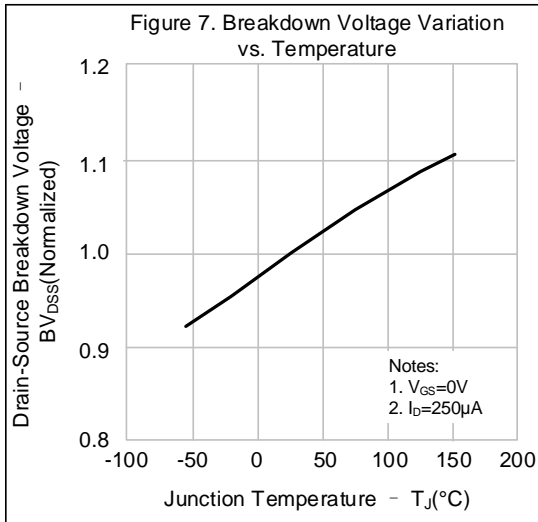
**Notes:**

1.  $L=79mH, I_{AS}=2.5A, V_{DD}=100V, R_G=25\Omega,$  starting  $T_J=25^\circ C$ ;
2. Pulse Test: Pulse width  $\leq 300\mu s,$  Duty cycle  $\leq 2\%$ ;
3. Essentially independent of operating temperature.

**TYPICAL CHARACTERISTICS**

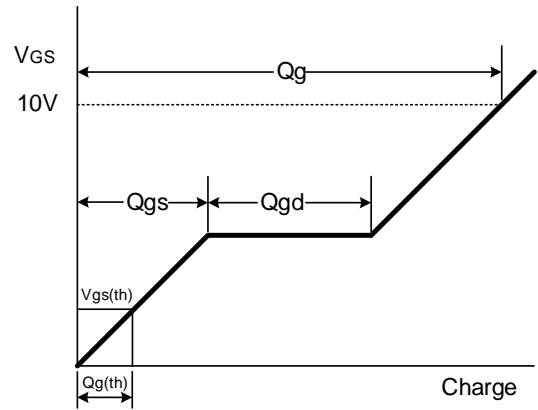
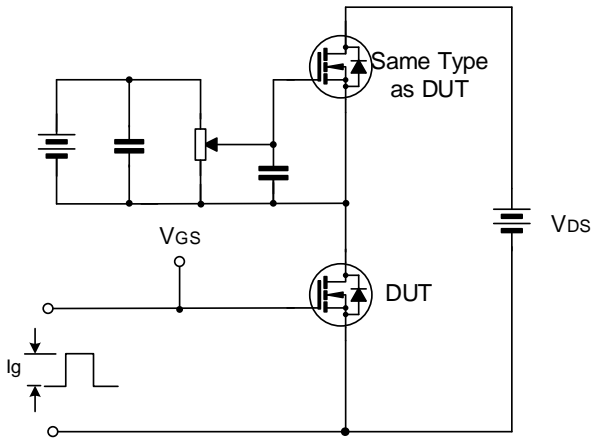


**TYPICAL CHARACTERISTICS (continued)**

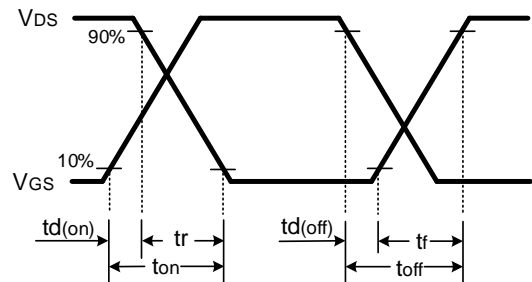
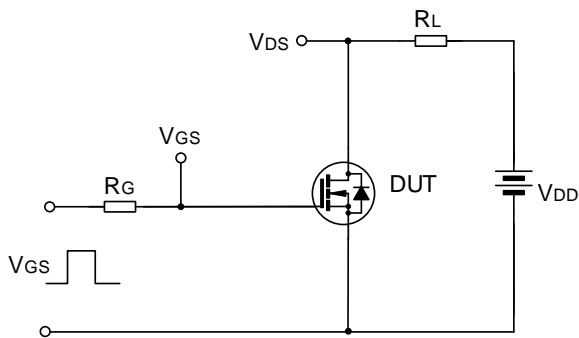


**TYPICAL TEST CIRCUIT**

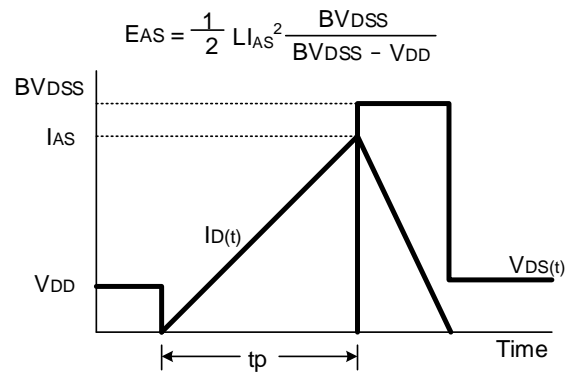
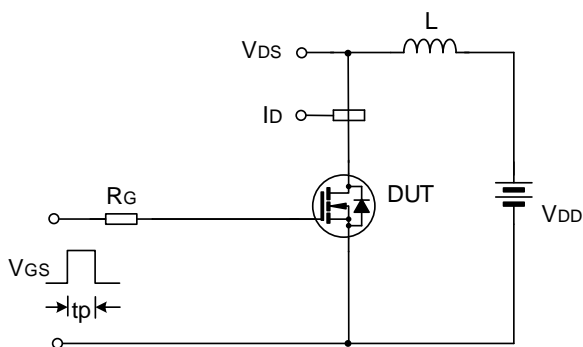
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



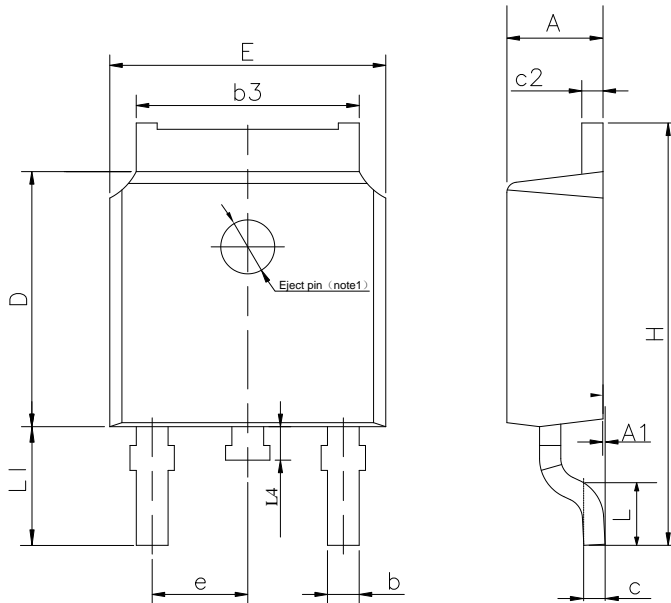
Undamped Inductive Switching Test Circuit & Waveform



**PACKAGE OUTLINE**

TO-252-2L

UNIT: mm



SYMBOL	MIN	NOM	MAX
A	2.10	2.30	2.50
A1	0	---	0.127
b	0.66	0.76	0.89
b3	5.10	5.33	5.46
c	0.45	---	0.65
c2	0.45	---	0.65
D	5.80	6.10	6.40
E	6.30	6.60	6.90
e	2.30TYP		
H	9.60	10.10	10.60
L	1.40	1.50	1.70
L1	2.90REF		
L4	0.60	0.80	1.00

**NOTE1** : There are two conditions for this position:has an eject pin or has no eject pin.

**Disclaimer :**

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Rev.: 1.7

Revision History:

1. Delete SVS7N70MJ、SVS7N70F、SVS7N70S and SVS7N70K
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Rev.: 1.6

Revision History:

1. Update the package outline of TO-251J-3L
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Rev.: 1.5

Revision History:

1. Modify the figure 3
- 

Rev.: 1.4

Revision History:

1. Modify the ordering information
- 

Rev.: 1.3

Revision History:

1. Modify the ordering information
  2. Modify the package information of TO-252-2L
- 

Rev.: 1.2

Revision History:

1. Modify the package information
- 

Rev.: 1.1

Revision History:

1. Add the package of TO-262-3L
- 

Rev.: 1.0

Revision History:

1. First release
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